

3rd Batch IC Taiwan Grand Challenge - Finalists Announcement

Team	Product / Solution	Nationality
3D Architech, Inc.	Metal manufacturing for energy efficiency improvement	UNITED STATES
AlixLabs AB	Atomic Layer Pitch Splitting: a breakthrough equipment solution for advanced semiconductor manufacturing	SWEDEN
Brilliant Silicon Technology Co., Ltd.	RF Chipset for Low Earth Orbit (LEO) user terminal	TAIWAN
DeepMentor Inc.	CNN AI IP-DeepLogCore & LLM AI IP-DeepTransformCore & AI Tools-DeepExpert	TAIWAN
EndoSemia Co., Ltd.	NBI Fusion AI-Powered ENT Endoscope: Next-Gen Nasopharyngeal Cancer Early Detection	TAIWAN
femtoAI	Sparse Processing Unit 001 (SPU-001)	UNITED STATES
HyperAccel	Bertha-Edge (BerthaE)	REPUBLIC OF KOREA
PurCity ApS	GapS panels	DENMARK

*Sorted in alphabetical order by team name